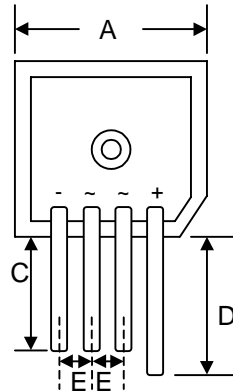


### Features

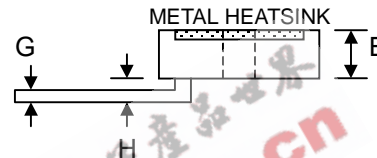
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space

### Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



KBPC-S		
Dim	Min	Max
A	28.40	28.70
B	10.97	11.23
C	13.90	—
D	19.10	—
E	5.10	—
G	1.20 Ø Typical	
H	3.05	3.60
All Dimensions in mm		



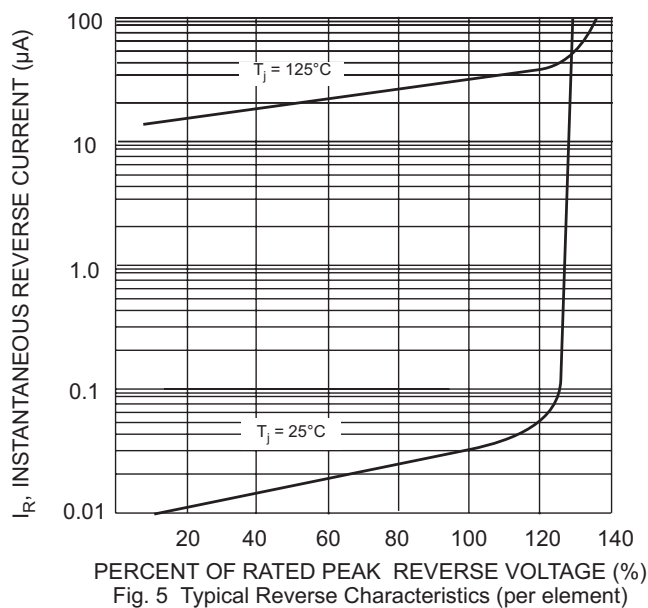
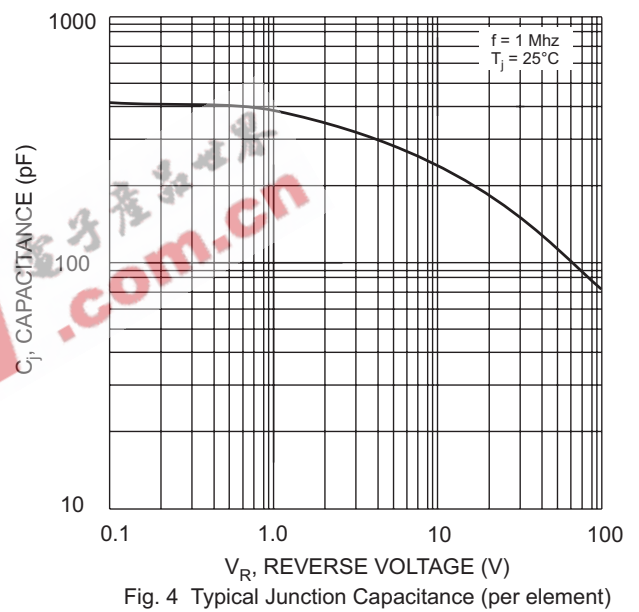
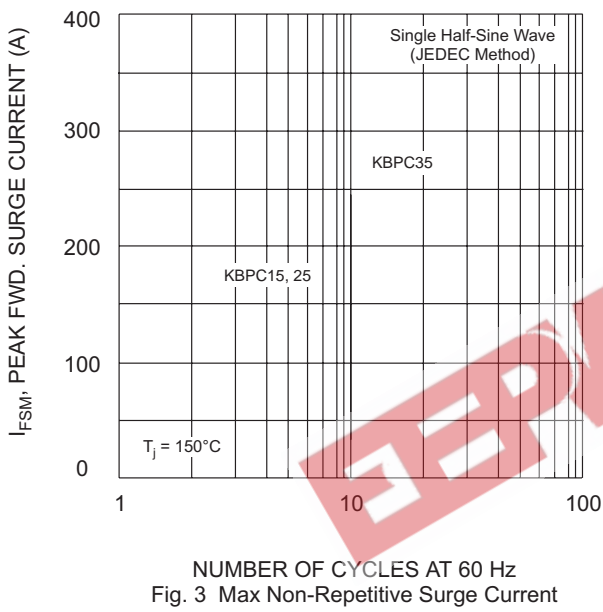
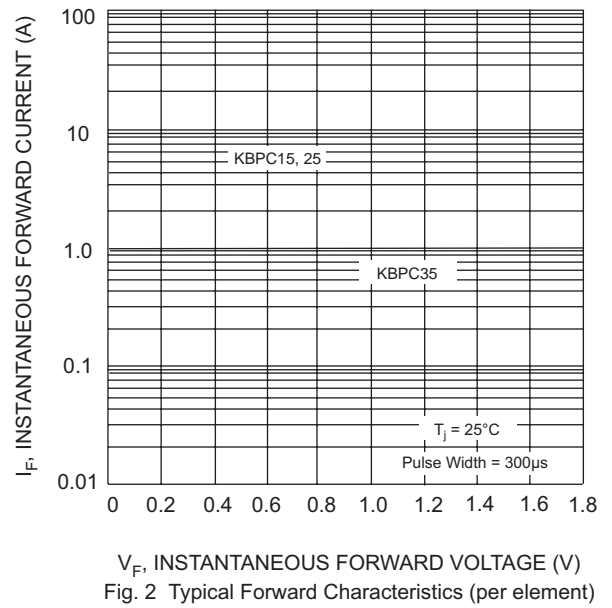
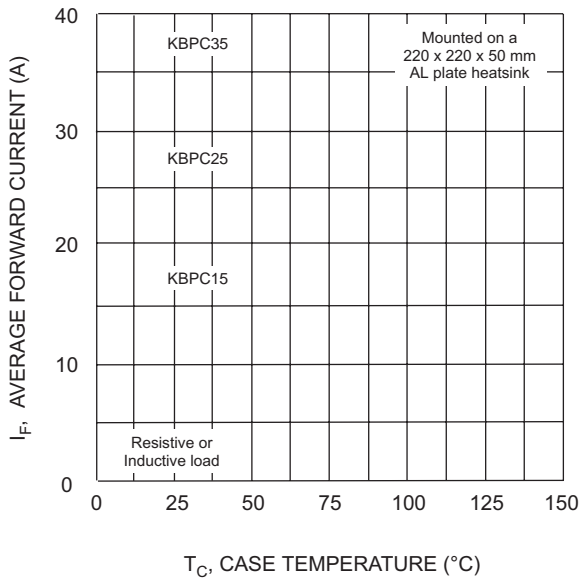
### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristics	Symbol	-00GS	-01GS	-02GS	-04GS	-06GS	-08GS	-10GS	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>								V
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	200	400	600	800	1000	
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current @T <sub>C</sub> = 55°C	I <sub>O</sub>				15				A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>				300				A
Forward Voltage Drop (per element)	V <sub>FM</sub>				1.1				V
Peak Reverse Current at Rated DC Blocking Voltage (per element)	I <sub>R</sub>				5.0				µA
					500				
I <sup>2</sup> t Rating for Fusing (t < 8.3ms) (Note 1)	I <sup>2</sup> t				374				A <sup>2</sup> s
					374				
					664				
Typical Thermal Resistance (per element) (Note 2)	R <sub>θJC</sub>				2.0				K/W
RMS Isolation Voltage from Case to Lead	V <sub>ISO</sub>				2500				V
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>				-65 to +150			°C	

Note: 1. Non-repetitive for t > 1ms and < 8.3ms.

2. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.



## ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
KBPCxx00GS	SIL Bridge	72 Units/Box
KBPCxx01GS	SIL Bridge	72 Units/Box
KBPCxx02GS	SIL Bridge	72 Units/Box
KBPCxx04GS	SIL Bridge	72 Units/Box
KBPCxx06GS	SIL Bridge	72 Units/Box
KBPCxx08GS	SIL Bridge	72 Units/Box
KBPCxx10GS	SIL Bridge	72 Units/Box

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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**WARNING:** DO NOT USE IN LIFE SUPPORT EQUIPMENT. WTE power semiconductor products are not authorized for use as critical components in life support devices or systems without the express written approval.

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